

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Rost et al.	Art Unit:	2811
Serial No.:	10/696,816	Examiner:	Crane, S.
Filing Date:	10/30/2003	Docket No.:	TI-35257
Customer No.:	23494	Conf. No.:	1301
Title: ONE MASK HIGH DENSITY CAPACITOR FOR INTEGRATED CIRCUITS			

RESPONSE UNDER EX PARTE QUAYLE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated November 2, 2006. They are respectfully submitted as a full and complete response to that Action.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 2 and 4-10 stand allowed.

Claims 2 and 4-10 are objected to due to an informality regarding the meaning of the term "cap layer". As noted by the Examiner and in the instant specification at paragraph [0013], cap layer 118 provides a bonding surface which offers better adhesion for ball bonds, bond wires, etc. than copper and while the aluminum cap layer is metal, it is not considered a metal interconnect level, but merely a capping layer to